

## TK PASTE CM-4230

### ◆ Product benefits

- Silver sintering, lead-free and high heat dissipation die bonding paste.
- Good sintering property at low temperature and no pressure (at 200°C in air or at 250°C in N<sub>2</sub> atmosphere).
- Can be densified by applying pressure during heating.
- High thermal conductivity of 170 W/m·k and high electrical conductivity on the order of 10<sup>-6</sup> Ω·cm.
- Long usable time (pot life) provides good workability.

### ◆ Typical properties

	Typical value	Remarks
Base resin	Pure sinter	Contains solvent, resinless
Silver content (wt.%)	85-95	
Appearance	Gray paste	
Viscosity (Pa·s)	40-55	E type viscosity meter: 5rpm at 25°C
Specific gravity (-)	6.2	At 25°C
Storage condition	-10°C or below	Shelf life: 6months after manufacture
How to use	Air puls dispensor	Internal diameter of needle: >0.2mm
Pot life (hr)	24	At 25°C
Typical curing schedule	60°C×1hr + 200°C×1hr	For under N <sub>2</sub> atmosphere: 60°C×1hr + 250°C×1hr
Specific resistance (Ω·cm)	6×10 <sup>-6</sup>	4-terminal method
Glass transition temperature (T <sub>g</sub> ) (°C)	T <sub>g</sub> less	DMA method
Storage modulus (GPa)	6.5	DMA method at 25°C
Coefficient of thermal expansion (ppm/°C)	18	α1
	-	α2

Data in this document is based on evaluation results and does NOT guarantee product characteristics at use.  
Make sure to try the product with equipment and adherend to be used.